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ABSTRACT

A power delivery network, circuit, and method reduce die package resonance of an integrated circuit (IC) die. Decoupling capacitors interact with equivalent series inductances (ESLs) of power conductors within a package carrier substrate create the die package resonance characteristic. In one form an anti-resonance tuning circuit has a first branch including a first inductance coupled to one of an IC die positive power supply conductor and an IC die negative power supply conductor, and a second branch coupled directly to a selected one of a carrier substrate positive or negative conductive structures, the second branch comprising a second inductance inductively coupled to the first inductance.

